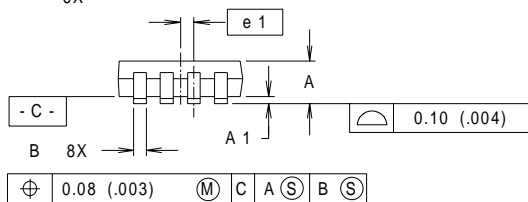
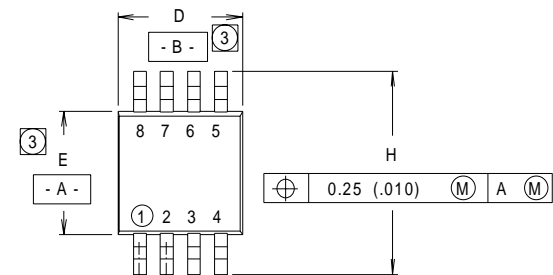


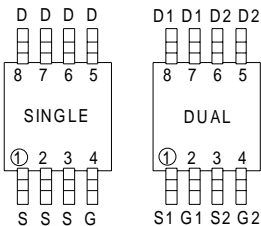
Package Outline

HEXFET Micro8 Outline

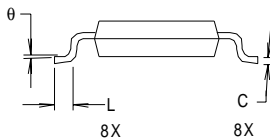
Dimensions are shown in millimeters (inches)



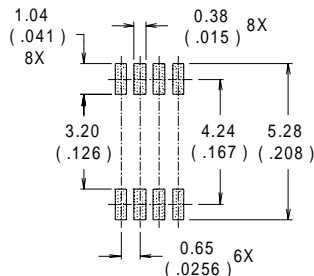
LEAD ASSIGNMENTS



DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.036	.044	0.91	1.11
A1	.004	.008	0.10	0.20
B	.010	.014	0.25	0.36
C	.005	.007	0.13	0.18
D	.116	.120	2.95	3.05
e	.0256 BASIC		0.65 BASIC	
e1	.0128 BASIC		0.33 BASIC	
E	.116	.120	2.95	3.05
H	.188	.198	4.78	5.03
L	.016	.026	0.41	0.66
θ	0°	6°	0°	6°



RECOMMENDED FOOTPRINT



NOTES:

1 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1982.

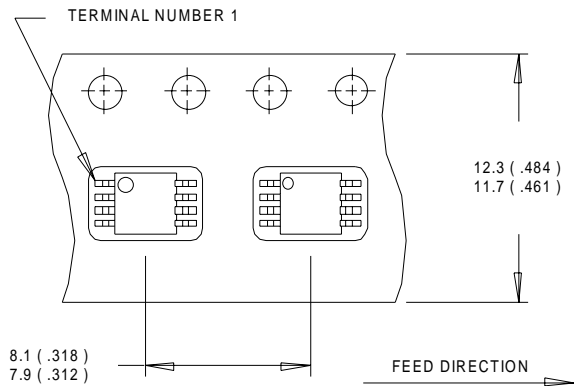
2 CONTROLLING DIMENSION : INCH.

3 DIMENSIONS DO NOT INCLUDE MOLD FLASH.

Tape & Reel Information

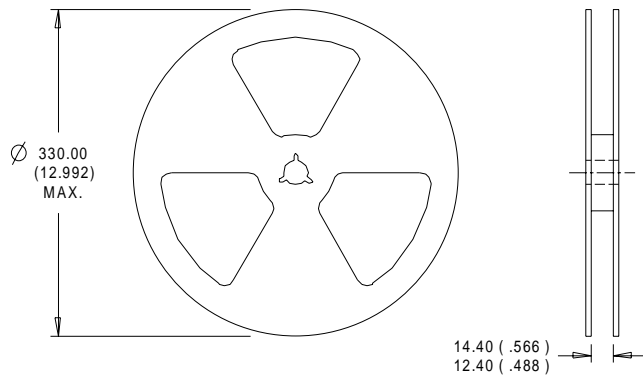
HEXFET Micro8

Dimensions are shown in millimeters (inches)



NOTES:

1. OUTLINE CONFORMS TO EIA-481 & EIA-541.
2. CONTROLLING DIMENSION : MILLIMETER.



NOTES:

1. CONTROLLING DIMENSION : MILLIMETER.
2. OUTLINE CONFORMS TO EIA-481 & EIA-541.

Part Marking Information

HEXFET Micro8

EXAMPLE : THIS IS AN IRF7501

